

GaAs Switch, FET, LNA IC

Recommended Soldering Conditions for Partial Heating

The following are the recommended soldering conditions for partial heating.

- Maximum Temperature (pin temperature): 350°C
- Time (per each side of the device): 3 seconds or less
- Maximum Chlorine Content of Rosin Flux: 0.2% (wt.)

Precautions:

1. Use a temperature adjustable soldering iron. Unnecessary heat increase may cause deterioration of the device.
2. Keep soldering iron away from the base of pins and the molding compound.
3. Soldering iron with $> 1M\Omega$ resistance grounded or with the soldering iron tip $> 1M\Omega$ grounded is recommended.
4. Electrostatic countermeasures are required during hand soldering. Avoid using materials that easily become charged electrically. Use conductive materials instead.